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(19) **United States**(12) **Patent Application Publication**  
**TSUNEKAWA**(10) **Pub. No.: US 2024/0237200 A1**(43) **Pub. Date: Jul. 11, 2024**(54) **ASSEMBLY SHEET AND METHOD FOR  
PRODUCING ASSEMBLY SHEET****Publication Classification**(71) Applicant: **NITTO DENKO CORPORATION,**  
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**ABSTRACT**

An assembly sheet includes a plurality of wiring circuit boards, a frame, and a reinforcement portion. The wiring circuit board has a support layer, a base insulating layer disposed on a one-surface of the support layer in a thickness direction, and a conductive pattern disposed on a one-surface of the base insulating layer in the thickness direction. The frame supports the wiring circuit board. The reinforcement portion reinforces the frame. The reinforcement portion is disposed on an other-surface of the frame in the thickness direction.

